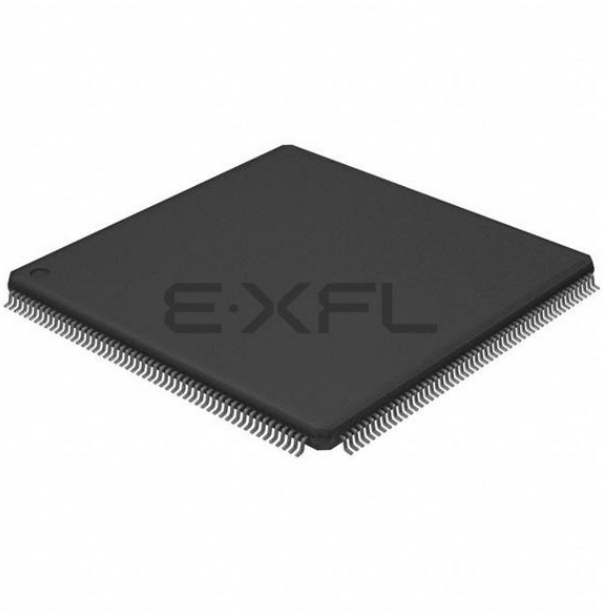

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"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	ARM® Cortex®-M4/M0
Core Size	32-Bit Dual-Core
Speed	204MHz
Connectivity	CANbus, EBI/EMI, Ethernet, I²C, IrDA, Microwire, QEI, SD, SPI, SSI, SSP, UART/USART, USB, USB OTG
Peripherals	Brown-out Detect/Reset, DMA, I²S, LCD, Motor Control PWM, POR, PWM, WDT
Number of I/O	142
Program Memory Size	512KB (512K x 8)
Program Memory Type	FLASH
EEPROM Size	16K x 8
RAM Size	136K x 8
Voltage - Supply (Vcc/Vdd)	2.2V ~ 3.6V
Data Converters	A/D 8x10b; D/A 1x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 105°C (TA)
Mounting Type	Surface Mount
Package / Case	208-LQFP
Supplier Device Package	208-LQFP (28x28)
Purchase URL	https://www.e-xfl.com/product-detail/nxp-semiconductors/lpc4353jbd208e

6. Pinning information

6.1 Pinning

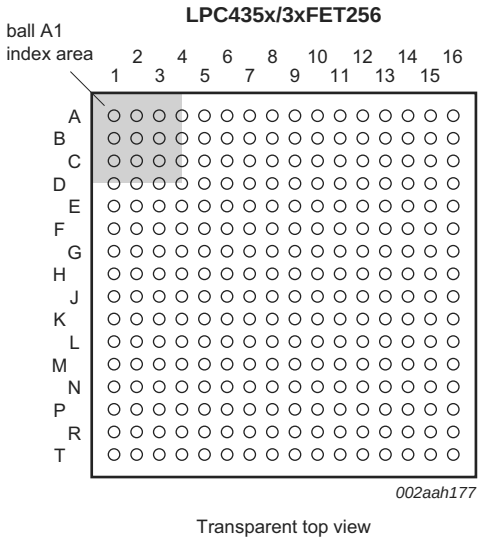


Fig 2. Pin configuration LBGA256 package

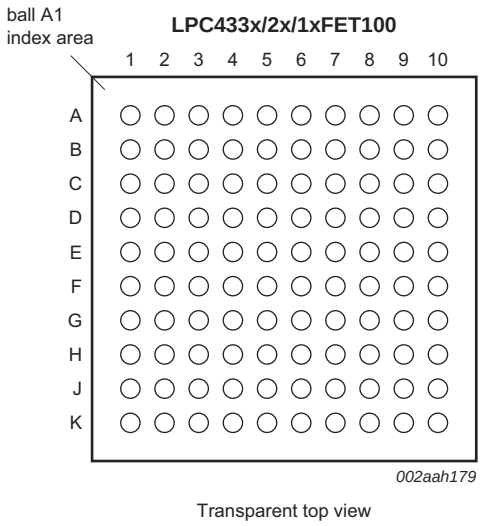


Fig 3. Pin configuration TFBGA100 package

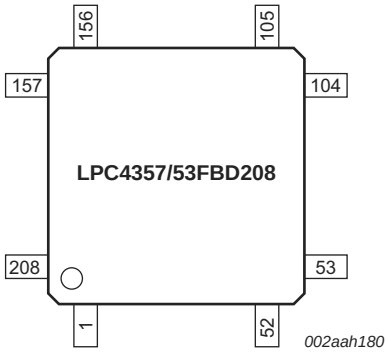


Fig 4. Pin configuration LQFP208 package

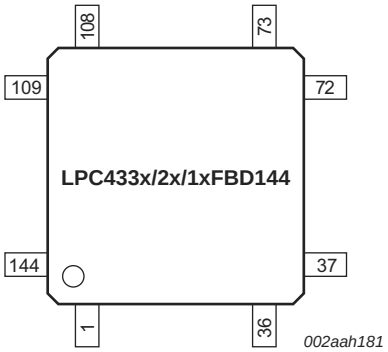


Fig 5. Pin configuration LQFP144 package

Table 3. Pin description *…continued*

Pin name	LBGA256	TFBGA100	LQFP208	LQFP144		Reset state [1]	Type	Description
P1_12	R9	K7	78	56	[2]	N; PU	I/O	**GPIO1[5] —** General purpose digital input/output pin.
							I	**U1_DCD —** Data Carrier Detect input for UART1.
							-	**R —** Function reserved.
							I/O	**EMC_D5 —** External memory data line 5.
							I	**T0_CAP1 —** Capture input 1 of timer 0.
							-	**R —** Function reserved.
							I/O	**SGPIO8 —** General purpose digital input/output pin.
							I/O	**SD_DAT3 —** SD/MMC data bus line 3.
P1_13	R10	H8	83	60	[2]	N; PU	I/O	**GPIO1[6] —** General purpose digital input/output pin.
							O	**U1_TXD —** Transmitter output for UART1.
							-	**R —** Function reserved.
							I/O	**EMC_D6 —** External memory data line 6.
							I	**T0_CAP0 —** Capture input 0 of timer 0.
							-	**R —** Function reserved.
							I/O	**SGPIO9 —** General purpose digital input/output pin.
							I	**SD_CD —** SD/MMC card detect input.
P1_14	R11	J8	85	61	[2]	N; PU	I/O	**GPIO1[7] —** General purpose digital input/output pin.
							I	**U1_RXD —** Receiver input for UART1.
							-	**R —** Function reserved.
							I/O	**EMC_D7 —** External memory data line 7.
							O	**T0_MAT2 —** Match output 2 of timer 0.
							-	**R —** Function reserved.
							I/O	**SGPIO10 —** General purpose digital input/output pin.
							-	**R —** Function reserved.
P1_15	T12	K8	87	62	[2]	N; PU	I/O	**GPIO0[2] —** General purpose digital input/output pin.
							O	**U2_TXD —** Transmitter output for USART2.
							I/O	**SGPIO2 —** General purpose digital input/output pin.
							I	**ENET_RXD0 —** Ethernet receive data 0 (RMII/MII interface).
							O	**T0_MAT1 —** Match output 1 of timer 0.
							-	**R —** Function reserved.
							I/O	**EMC_D8 —** External memory data line 8.
							-	**R —** Function reserved.

Table 3. Pin description *…continued*

Pin name	LBGA256	TFBGA100	LQFP208	LQFP144		Reset state [1]	Type	Description
P9_1	N6	-	66	-	[2]	N; PU	I/O	**GPIO4[13] —** General purpose digital input/output pin.
							O	**MCOA2 —** Motor control PWM channel 2, output A.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
							I/O	**I2S0_TX_WS —** Transmit Word Select. It is driven by the master and received by the slave. Corresponds to the signal WS in the *I^2S-bus specification*.
							I	**ENET_RX_ER —** Ethernet receive error (MII interface).
							I/O	**SGPIO1 —** General purpose digital input/output pin.
							I/O	**SSP0_MISO —** Master In Slave Out for SSP0.
P9_2	N8	-	70	-	[2]	N; PU	I/O	**GPIO4[14] —** General purpose digital input/output pin.
							O	**MCOB2 —** Motor control PWM channel 2, output B.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
							I/O	**I2S0_TX_SDA —** I2S transmit data. It is driven by the transmitter and read by the receiver. Corresponds to the signal SD in the *I^2S-bus specification*.
							I	**ENET_RXD3 —** Ethernet receive data 3 (MII interface).
							I/O	**SGPIO2 —** General purpose digital input/output pin.
							I/O	**SSP0_MOSI —** Master Out Slave in for SSP0.
P9_3	M6	-	79	-	[2]	N; PU	I/O	**GPIO4[15] —** General purpose digital input/output pin.
							O	**MCOA0 —** Motor control PWM channel 0, output A.
							O	**USB1_IND1 —** USB1 Port indicator LED control output 1.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
							I	**ENET_RXD2 —** Ethernet receive data 2 (MII interface).
							I/O	**SGPIO9 —** General purpose digital input/output pin.
							O	**U3_TXD —** Transmitter output for USART3.
P9_4	N10	-	92	-	[2]	N; PU	-	**R —** Function reserved.
							O	**MCOB0 —** Motor control PWM channel 0, output B.
							O	**USB1_IND0 —** USB1 Port indicator LED control output 0.
							-	**R —** Function reserved.
							I/O	**GPIO5[17] —** General purpose digital input/output pin.
							O	**ENET_TXD2 —** Ethernet transmit data 2 (MII interface).
							I/O	**SGPIO4 —** General purpose digital input/output pin.
							I	**U3_RXD —** Receiver input for USART3.

Table 3. Pin description *…continued*

Pin name	LBGA256	TFBGA100	LQFP208	LQFP144		Reset state [1]	Type	Description
PE_10	E14	-	154	-	[2]	N; PU	-	**R —** Function reserved.
							I	**CTIN_3 —** SCT input 3. Capture input 1 of timer 1.
							O	**U1_DTR —** Data Terminal Ready output for UART 1. Can also be configured to be an RS-485/EIA-485 output enable signal for UART 1.
							I/O	**EMC_D29 —** External memory data line 29.
							I/O	**GPIO7[10] —** General purpose digital input/output pin.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
PE_11	D16	-	-	-	[2]	N; PU	-	**R —** Function reserved.
							O	**CTOUT_12 —** SCT output 12. Match output 3 of timer 3.
							O	**U1_TXD —** Transmitter output for UART 1.
							I/O	**EMC_D30 —** External memory data line 30.
							I/O	**GPIO7[11] —** General purpose digital input/output pin.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
PE_12	D15	-	-	-	[2]	N; PU	-	**R —** Function reserved.
							O	**CTOUT_11 —** SCT output 11. Match output 3 of timer 2.
							I	**U1_RXD —** Receiver input for UART 1.
							I/O	**EMC_D31 —** External memory data line 31.
							I/O	**GPIO7[12] —** General purpose digital input/output pin.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
PE_13	G14	-	-	-	[2]	N; PU	-	**R —** Function reserved.
							O	**CTOUT_14 —** SCT output 14. Match output 2 of timer 3.
							I/O	**I2C1_SDA —** I^2C1 data input/output (this pin does not use a specialized I2C pad).
							O	**EMC_DQMOUT3 —** Data mask 3 used with SDRAM and static devices.
							I/O	**GPIO7[13] —** General purpose digital input/output pin.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
							-	**R —** Function reserved.

7.5 AHB multilayer matrix

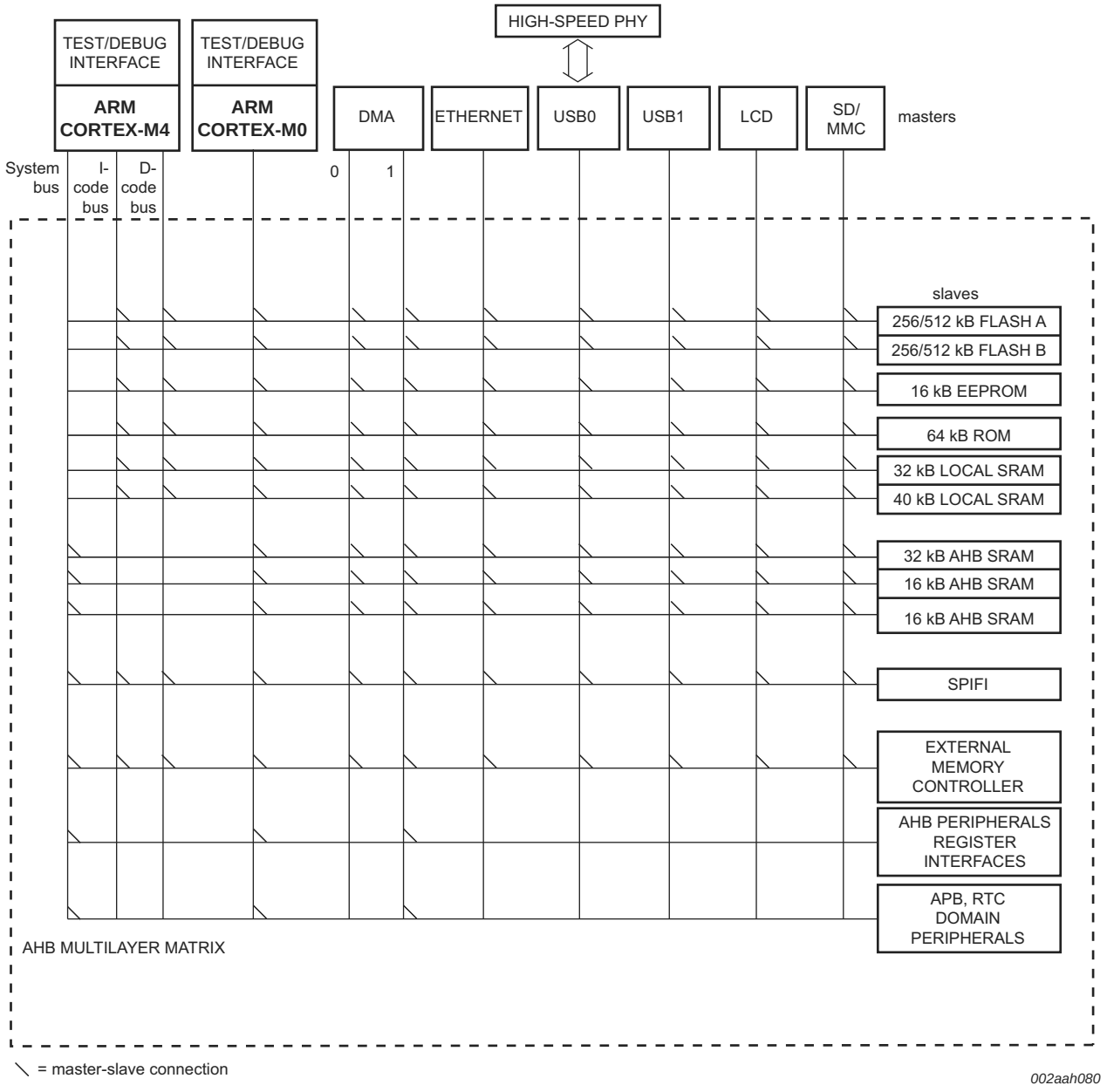


Fig 6. AHB multilayer matrix master and slave connections

7.6 Nested Vectored Interrupt Controller (NVIC)

The NVIC is an integral part of the Cortex-M4. The tight coupling to the CPU allows for low interrupt latency and efficient processing of late arriving interrupts.

The ARM Cortex-M0 co-processor has its own NVIC with 32 vectored interrupts. Most peripheral interrupts are shared between the Cortex-M0 and Cortex-M4 NVICs.

7.18.5 High-speed USB Host/Device/OTG interface (USB0)

Remark: USB0 is available on the following parts: LPC435x, LPC433x, LPC432x. USB0 is not available on the LPC431x parts.

The USB OTG module allows the LPC435x/3x/2x/1x to connect directly to a USB Host such as a PC (in device mode) or to a USB Device in host mode.

7.18.5.1 Features

- Contains UTMI+ compliant high-speed transceiver (PHY).
- Complies with *Universal Serial Bus specification 2.0*.
- Complies with *USB On-The-Go supplement*.
- Complies with *Enhanced Host Controller Interface Specification*.
- Supports auto USB 2.0 mode discovery.
- Supports all high-speed USB-compliant peripherals.
- Supports all full-speed USB-compliant peripherals.
- Supports software Host Negotiation Protocol (HNP) and Session Request Protocol (SRP) for OTG peripherals.
- Supports interrupts.
- Supports Start Of Frame (SOF) frame length adjust.
- This module has its own, integrated DMA engine.
- USB interface electrical test software included in ROM USB stack.

7.18.6 High-speed USB Host/Device interface with ULPI (USB1)

Remark: USB1 is available on the following parts: LPC435x and LPC433x. USB1 is not available on the LPC432x and LPC431x parts.

The USB1 interface can operate as a full-speed USB Host/Device interface or can connect to an external ULPI PHY for High-speed operation.

7.18.6.1 Features

- Complies with *Universal Serial Bus specification 2.0*.
- Complies with *Enhanced Host Controller Interface Specification*.
- Supports auto USB 2.0 mode discovery.
- Supports all high-speed USB-compliant peripherals if connected to external ULPI PHY.
- Supports all full-speed USB-compliant peripherals.
- Supports interrupts.
- Supports Start Of Frame (SOF) frame length adjust.
- This module has its own, integrated DMA engine.
- USB interface electrical test software included in ROM USB stack.

7.18.7 LCD controller

Remark: The LCD controller is only available on parts LPC435x. LCD is not available on parts LPC433x, LPC432x, and LPC431x.

Wake-up from sleep mode is caused by an interrupt or event in the core's NVIC. The interrupt is captured in the NVIC and an event is captured in the Event router. Both cores can wake up from sleep mode independently of each other.

Wake-up from the Power-down modes, Deep-sleep, Power-down, and Deep power-down, is caused by an event on the WAKEUP pins or an event from the RTC or alarm timer.

When waking up from Deep power-down mode, the part resets and attempts to boot.

7.23.10 Power control

The LPC435x/3x/2x/1x feature several independent power domains to control power to the core and the peripherals (see Figure 9). The RTC and its associated peripherals (the alarm timer, the CREG block, the OTP controller, the back-up registers, and the event router) are located in the RTC power-domain. The main regulator or a battery supply can power the RTC. A power selector switch ensures that the RTC block is always powered on.

10. Static characteristics

Table 11. Static characteristics

T_{amb} = −40 °C to +105 °C, unless otherwise specified.

Symbol	Parameter	Conditions		Min	Typ[1]	Max	Unit
Supply pins							
$V_{DD(IO)}$	input/output supply voltage		[17]	2.4	-	3.6	V
$V_{DD(REG)(3V3)}$	regulator supply voltage (3.3 V)		[2]	2.4	-	3.6	V
$V_{DDA(3V3)}$	analog supply voltage (3.3 V)	on pin VDDA		2.4	-	3.6	V
		on pins USB0_VDDA3V3_ DRIVER and USB0_VDDA3V3		3.0	3.3	3.6	V
V_{BAT}	battery supply voltage		[2]	2.4	-	3.6	V
$V_{prog(pf)}$	polyfuse programming voltage	on pin VPP (for OTP)	[3]	2.7	-	3.6	V
$I_{prog(pf)}$	polyfuse programming current	on pin VPP; OTP programming time ≤ 1.6 ms		-	-	30	mA
$I_{DD(REG)(3V3)}$	regulator supply current (3.3 V)	Active mode; ARM Cortex-M0 core in reset; code `while(1){}` executed from RAM; all peripherals disabled; PLL1 enabled					
		CCLK = 12 MHz	[4]	-	10	-	mA
		CCLK = 60 MHz	[4]		28	-	mA
		CCLK = 120 MHz	[4]	-	51	-	mA
		CCLK = 180 MHz	[4]	-	74	-	mA
		CCLK = 204 MHz	[4]	-	83	-	mA
$I_{DD(REG)(3V3)}$	regulator supply current (3.3 V)	after WFE/WFI instruction executed from RAM; all peripherals disabled; ARM Cortex-M0 core in reset					
		sleep mode	[4][5]	-	8.8	-	mA
		deep-sleep mode	[4]	-	145	-	µA
		power-down mode	[4]	-	23	-	µA
		deep power-down mode	[4][6]	-	0.05	-	µA
		deep power-down mode; VBAT floating	[4]	-	3.0	-	µA
I_{BAT}	battery supply current	V_{BAT} = 3.0 V; $V_{DD(REG)(3V3)}$ = 3.3 V	[7]	-		0.1	nA

Table 11. Static characteristics *…continued*
T_{amb} = −40 °C to +105 °C, unless otherwise specified.

Symbol	Parameter	Conditions		Min	Typ[1]	Max	Unit
I_{BAT}	battery supply current	$V_{DD(REG)(3V3)}$ = 3.3 V; V_{BAT} = 3.6 V	[8]				
		deep-sleep mode		-	1.5	-	µA
		power-down mode	[8]	-	1.5	-	µA
		deep power-down mode	[8]	-	1.5	-	µA
I_{BAT}	battery supply current	Deep power-down mode; RTC running; $V_{DD(REG)}$ = VDDA = VDDIO = 0 V; V_{BAT} = 3.3 V		-	3.0	-	µA
		$V_{DD(REG)(3V3)}$ = V_{BAT} = 3.3 V		-	1.5	-	µA
$I_{DD(IO)}$	I/O supply current	deep sleep mode		-	< 0.1	-	µA
		power-down mode		-	< 0.1	-	µA
		deep power-down mode		-	< 0.1	-	µA
I_{DDA}	Analog supply current	on pin VDDA;	[10]	-	0.4	-	
		deep sleep mode					µA
		power-down mode	[10]	-	0.4	-	µA
		deep power-down mode	[10]	-	0.007	-	µA
$\overline{\text{RESET}}$ pin							
V_{IH}	HIGH-level input voltage		[9]	$0.8 \times (V_{ps} - 0.35)$	-	5.5	V
V_{IL}	LOW-level input voltage		[9]	−0.5	-	$0.3 \times (V_{ps} - 0.1)$	V
V_{hys}	hysteresis voltage		[9]	$0.05 \times (V_{ps} - 0.35)$	-	-	V
Standard I/O pins - normal drive strength							
C_I	input capacitance			-	-	2	pF
I_{LL}	LOW-level leakage current	V_I = 0 V; on-chip pull-up resistor disabled		-	3	-	nA
I_{LH}	HIGH-level leakage current	$V_I = V_{DD(IO)}$; on-chip pull-down resistor disabled		-	3	-	nA
		V_I = 5 V; T_{amb} = 25 °C		-	0.5	-	nA
		V_I = 5 V; T_{amb} = 105 °C		-	40	-	nA
I_{OZ}	OFF-state output current	V_O = 0 V to $V_{DD(IO)}$; on-chip pull-up/down resistors disabled; absolute value		-	3	-	nA
V_I	input voltage	pin configured to provide a digital function;		0	-	5.5	V
		$V_{DD(IO)} \geq$ 2.4 V					
		$V_{DD(IO)}$ = 0 V		0	-	3.6	V

11.14 SSP/SPI timing diagrams

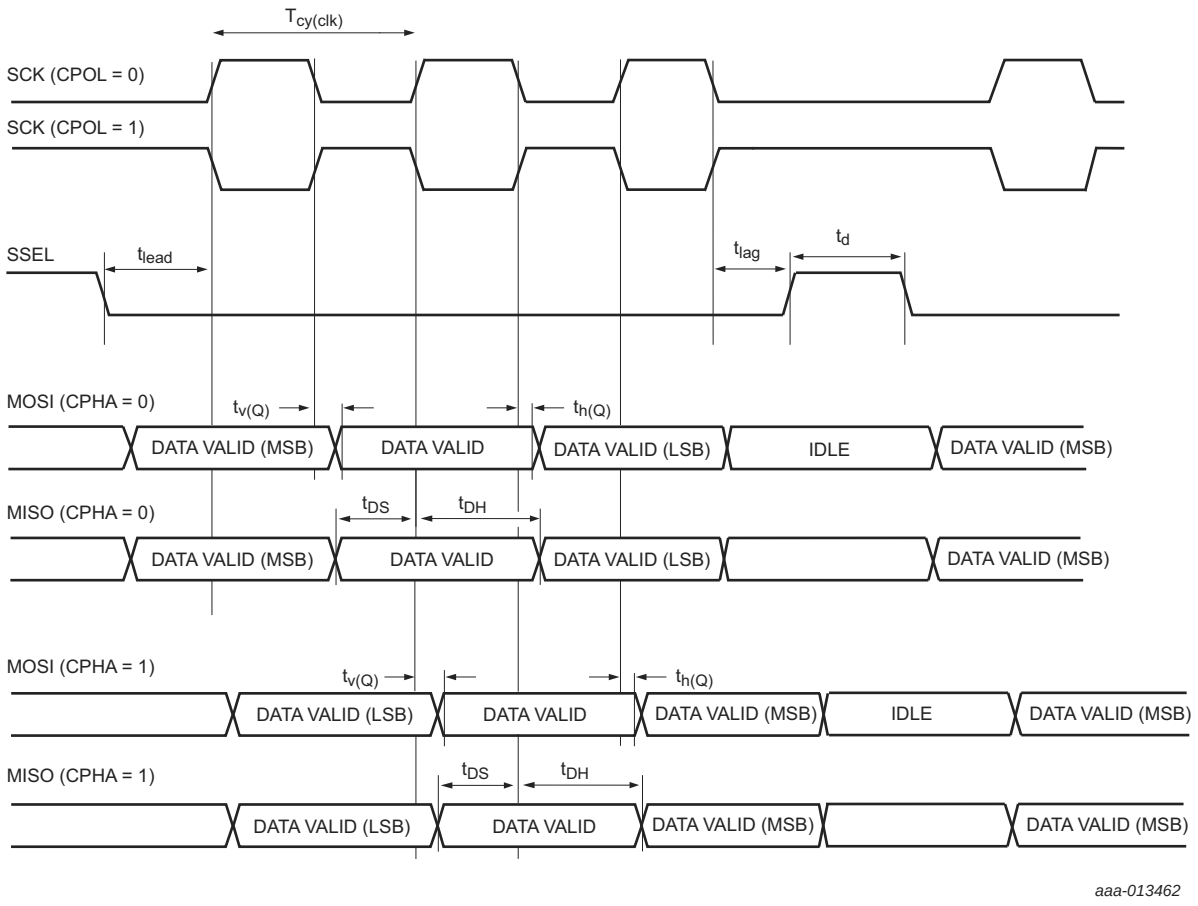


Fig 31. SSP in SPI mode and SPI master timing

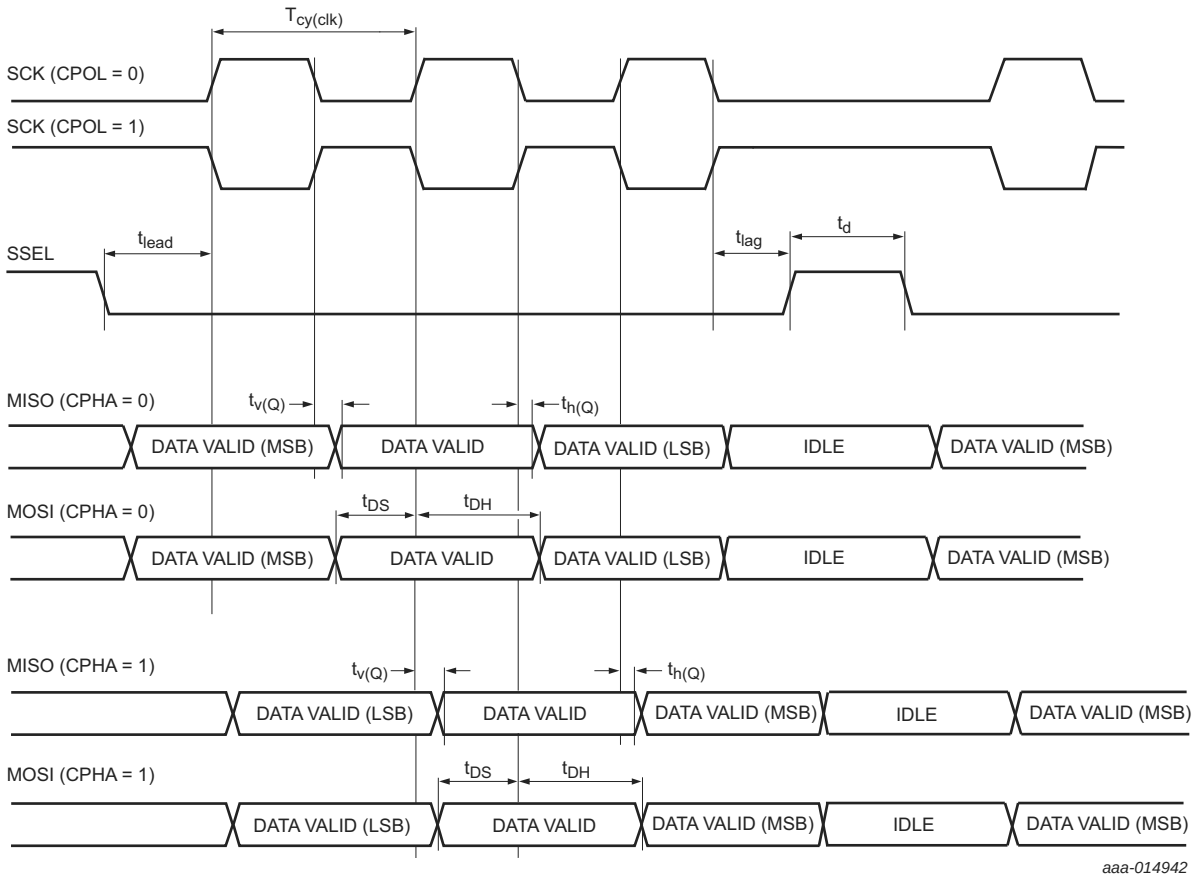


Fig 32. SSP in SPI mode and SPI slave timing

11.15 SPIFI

Table 29. Dynamic characteristics: SPIFI

T_{amb} = −40 °C to 105 °C; 2.4 V ≤ $V_{DD(REG)(3V3)}$ ≤ 3.6 V; 2.7 V ≤ $V_{DD(IO)}$ ≤ 3.6 V. C_L = 20 pF. Sampled at 90 % and 10 % of the signal level. EHS = 1 for all pins. Simulated values.

Symbol	Parameter	Min	Max	Unit
$T_{cy(clk)}$	clock cycle time	9.6	-	ns
t_{DS}	data set-up time	3.2	-	ns
t_{DH}	data hold time	0	-	ns
$t_{v(Q)}$	data output valid time	-	3.2	ns
$t_{h(Q)}$	data output hold time	0.6	-	ns

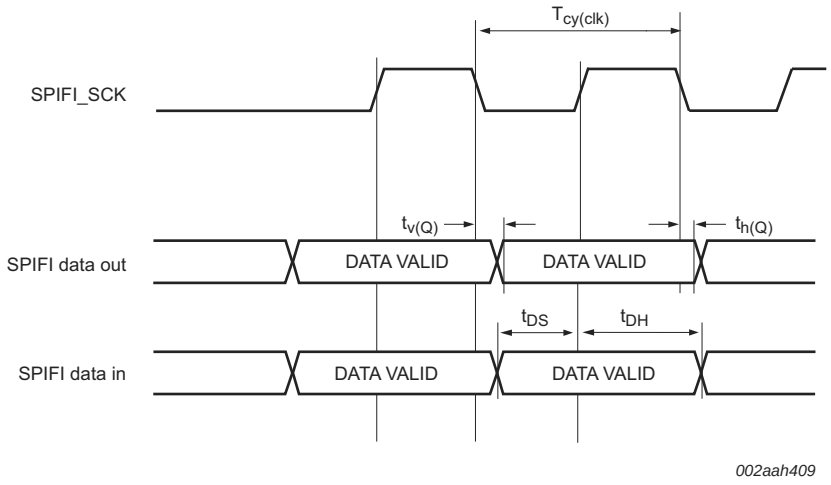


Fig 33. SPIFI timing (Mode 0)

11.16 SGPIO timing

The following considerations apply to SGPIO timing:

- SGPIO input signals are synchronized by the internal clock SGPIO_CLOCK. To guarantee that no samples are missed, all input signals should have a duration of at least one SGPIO_CLOCK cycle plus the set-up and hold times.
- When an external clock input is used to generate output data, synchronization causes a latency of at least one SGPIO_CLOCK cycle. The maximum output data rate is one output every two SGPIO_CLOCK cycles.
- Synchronization also causes a latency of one SGPIO_CLOCK cycle when sampling several inputs. This may cause inputs with very similar timings to be sampled with a difference of one SGPIO_CLOCK cycle.

Table 30. Dynamic characteristics: SGPIO

T_{amb} = −40 °C to +105 °C; 2.4 V ≤ $V_{DD(REG)(3V3)}$ ≤ 3.6 V; 2.7 V ≤ $V_{DD(IO)}$ ≤ 3.6 V. Simulated values.

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
$t_{su(D)}$	data input set-up time			2	-	-	ns
$t_{h(D)}$	data input hold time		[1]	T_{SGPIO} + 2	-	-	ns
$t_{su(D)}$	data input set-up time	sampled by SGPIO_CLOCK	[1]	T_{SGPIO} + 2	-	-	ns
$t_{h(D)}$	data input hold time	sampled by SGPIO_CLOCK	[1]	T_{SGPIO} + 2	-	-	ns
$t_{v(Q)}$	data output valid time		[1]	-	-	2 × T_{SGPIO}	ns
$t_{h(Q)}$	data output hold time		[1]	T_{SGPIO}	-		ns
$t_{v(Q)}$	data output valid time	sampled by SGPIO_CLOCK	[1]	-3	-	3	ns
$t_{h(Q)}$	data output hold time	sampled by SGPIO_CLOCK	[1]	-3	-	3	ns

[1] SGPIO_CLOCK is the internally generated SGPIO clock. $T_{SGPIO} = 1/f_{SGPIO\_CLOCK}$.

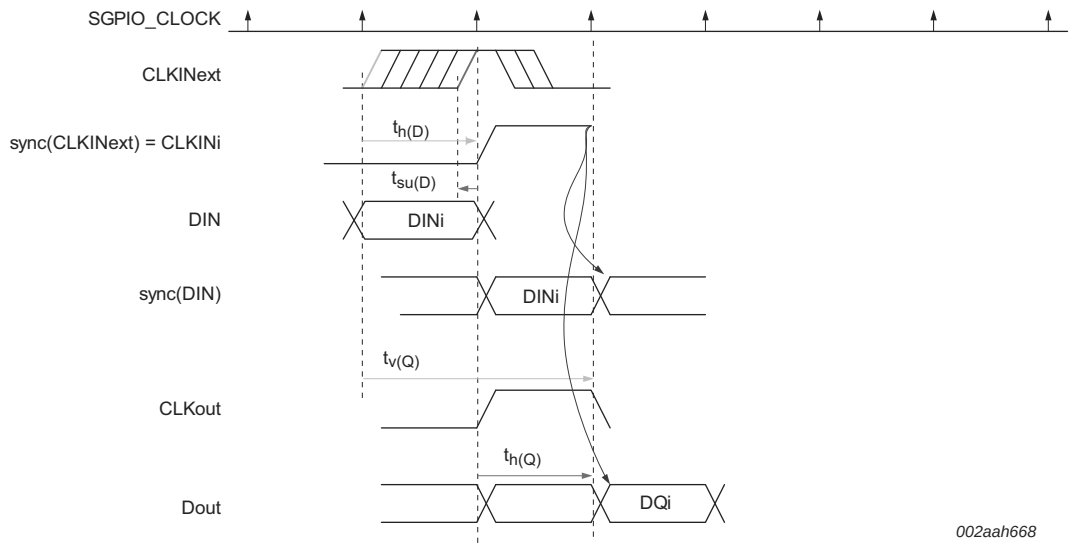


Fig 34. SGPIO timing

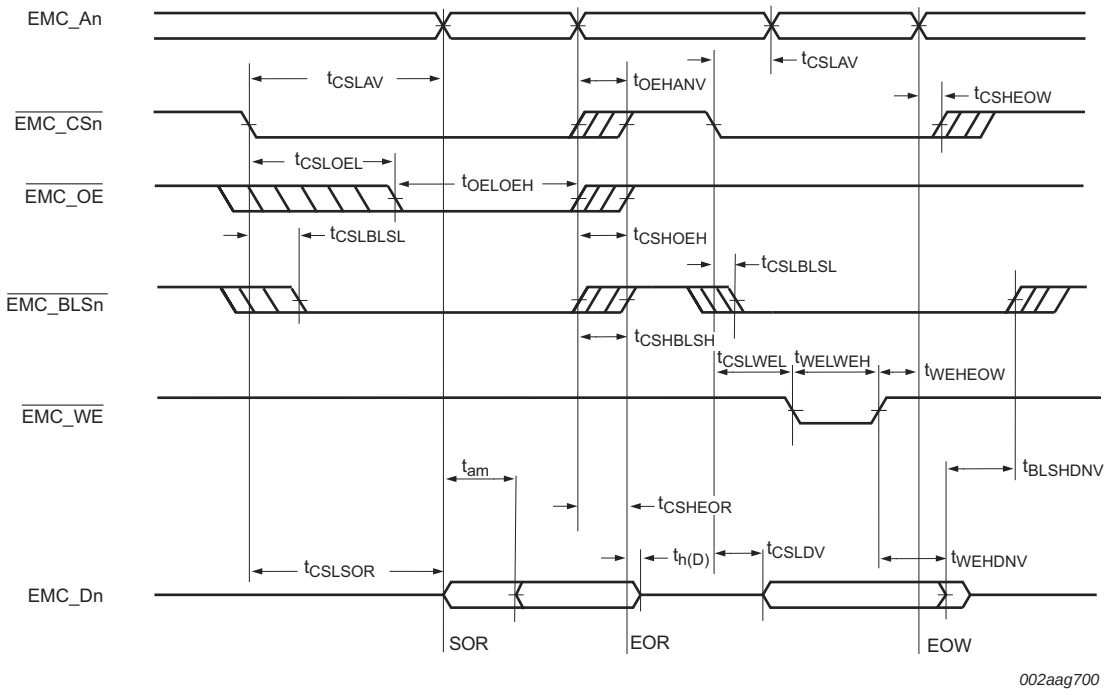
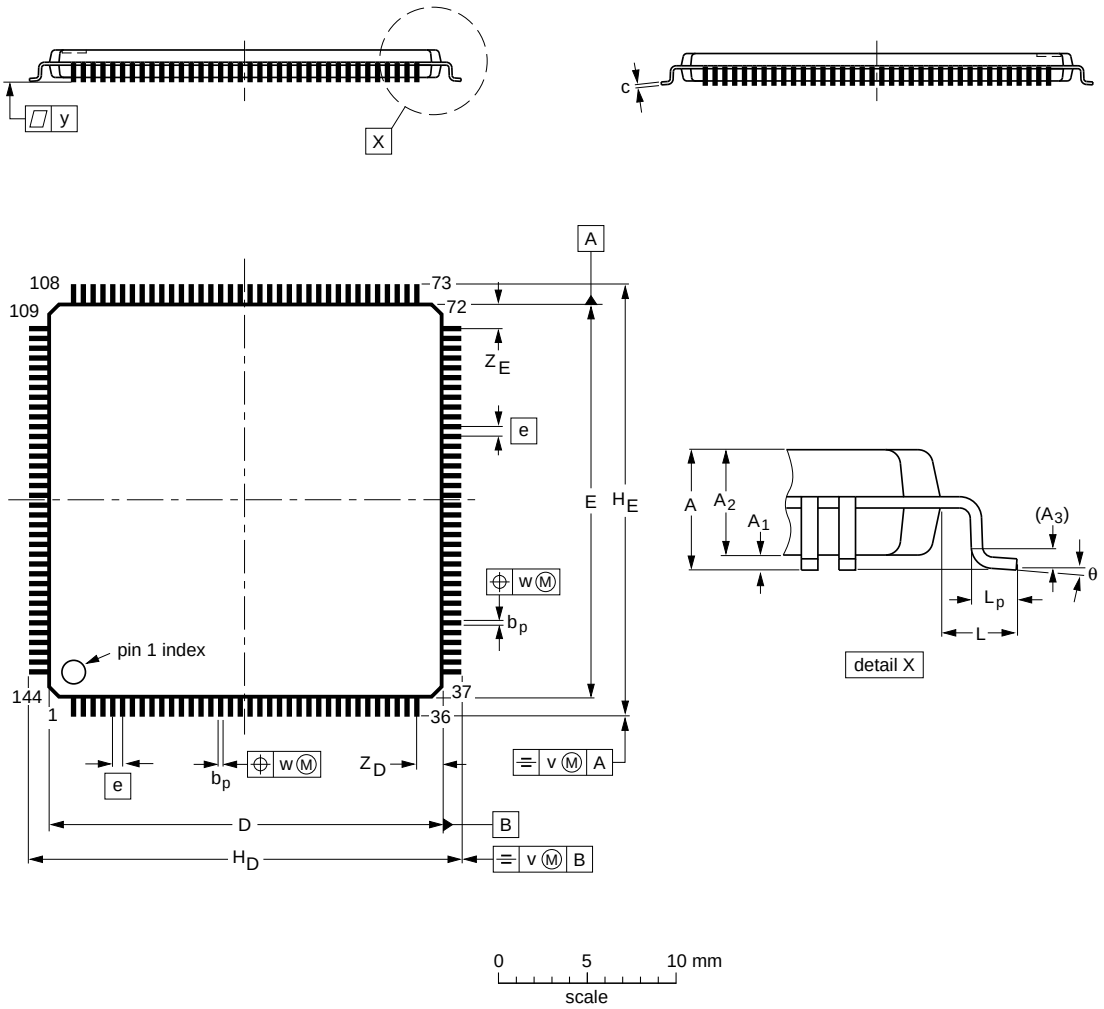


Fig 36. External static memory read/write access (PB = 1)

LQFP144: plastic low profile quad flat package; 144 leads; body 20 x 20 x 1.4 mm **SOT486-1**



DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A_1	A_2	A_3	b_p	c	$D^{(1)}$	$E^{(1)}$	e	H_D	H_E	L	L_p	v	w	y	$Z_D^{(1)}$	$Z_E^{(1)}$	θ
mm	1.6	0.15 0.05	1.45 1.35	0.25	0.27 0.17	0.20 0.09	20.1 19.9	20.1 19.9	0.5	22.15 21.85	22.15 21.85	1	0.75 0.45	0.2	0.08	0.08	1.4 1.1	1.4 1.1	7^o 0^o

Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT486-1	136E23	MS-026				~~00-03-14~~ 03-02-20

Fig 54. Package outline for the LQFP144 package

16. Abbreviations

Table 46. Abbreviations

Acronym	Description
ADC	Analog-to-Digital Converter
AHB	Advanced High-performance Bus
APB	Advanced Peripheral Bus
API	Application Programming Interface
BOD	BrownOut Detection
CAN	Controller Area Network
CMAC	Cipher-based Message Authentication Code
CSMA/CD	Carrier Sense Multiple Access with Collision Detection
DAC	Digital-to-Analog Converter
DC-DC	Direct Current-to-Direct Current
DMA	Direct Memory Access
GPIO	General Purpose Input/Output
IRC	Internal RC
IrDA	Infrared Data Association
JTAG	Joint Test Action Group
LCD	Liquid Crystal Display
LSB	Least Significant Bit
MAC	Media Access Control
MCU	MicroController Unit
MIIM	Media Independent Interface Management
n.c.	not connected
OHCI	Open Host Controller Interface
OTG	On-The-Go
PHY	Physical Layer
PLL	Phase-Locked Loop
PMC	Power Mode Control
PWM	Pulse Width Modulator
RIT	Repetitive Interrupt Timer
RMII	Reduced Media Independent Interface
SDRAM	Synchronous Dynamic Random Access Memory
SIMD	Single Instruction Multiple Data
SPI	Serial Peripheral Interface
SSI	Serial Synchronous Interface
SSP	Synchronous Serial Port
UART	Universal Asynchronous Receiver/Transmitter
ULPI	UTMI+ Low Pin Interface
USART	Universal Synchronous Asynchronous Receiver/Transmitter
USB	Universal Serial Bus
UTMI	USB2.0 Transceiver Macrocell Interface

17. References

[1] LPC43xx User manual UM10503:
http://www.nxp.com/documents/user_manual/UM10503.pdf

[2] LPC43xx Errata sheet:
http://www.nxp.com/documents/errata_sheet/ES_LPC43XX.pdf

Table 47. Revision history *…continued*

Document ID	Release date	Data sheet status	Change notice	Supersedes
Modifications:	• SD/MMC timing data updated. See Table 35 “Dynamic characteristics: SD/MMC”. • IEEE standard 802.3 compliance added to Section 11.18. Covers Ethernet dynamic characteristics of ENET_MDIO and ENET_MDC signals. • SSP master mode timing diagram updated with SSEL timing parameters. See Figure 31 “SSP in SPI mode and SPI master timing”. • Parameters t_{lead}, t_{lag}, and t_d added in Table 25 “Dynamic characteristics: SSP pins in SPI mode”. • Parameter t_{CSLWEL} with condition PB = 1 corrected: (WAITWEN + 1) × $T_{cy(clk)}$ added. See Table 29 “Dynamic characteristics: Static asynchronous external memory interface”. • Parameter $t_{CSLBLSL}$ with condition PB = 0 corrected: (WAITWEN + 1) × $T_{cy(clk)}$ added. See Table 29 “Dynamic characteristics: Static asynchronous external memory interface”. • Removed restriction on C_CAN bus usage. See CAN.1 errata in Ref. 2. • General-purpose OTP size corrected.			
LPC435X_3X_2X_1X v.3	20121206	Preliminary data sheet	-	LPC4357_53_37_33 v.2.1
Modifications:	• TFBGA180 packages removed. • Part LPC432x and LPC431x added. • SCT dither engine added and SCT bi-directional event enable features added. • Figure 10 “Dual-core debug configuration” added. • T = 105 °C data added in Figure 20 to Figure 23. • Change symbol names and parameter names in Table 21. • Parameter I_{LH} updated for condition V_I = 5 V and T_{amb} = 25 °C/105 °C in Table 11. • Power consumption data added in Section 10.1. • SPIFI dynamic characteristics added in Section 11.16. • IRC accuracy corrected to ± 2 % for T_{amb} = -40 °C to 0 °C and T_{amb} = 85 °C to 105 °C. • Pull-up and Pull-down current data (Figure 24 and Figure 25) updated with data for T_{amb} = 105 °C. • SPIFI maximum data rate changed to 52 MB per second. • Recommendation for V_{BAT} use added: The recommended operating condition for the battery supply is $V_{DD(REG)(3V3)} > V_{BAT}$ + 0.2 V. • Table 14 “Band gap characteristics” added. • Section 7.23.9 “Power Management Controller (PMC)” added. • Description of ADC pins on digital/analog input pins changed. Each input to the ADC is connected to ADC0 and ADC1. See Table 3. • OTP memory size changed to 64 bit. • Use of C_CAN peripheral restricted in Section 2. • ADC channels limited to a total of 8 channels shared between ADC0 and ADC1.			
LPC4357_53_37_33 v.2.1	20120904	Preliminary data sheet	-	LPC4357_53_37_33 v.2
Modifications:	• SSP0 boot pin functions corrected in Table 5 and Table 4. Pin P3_3 = SSP0_SCK, pin P3_6 = SSP0_SSEL, pin P3_7 = SSP0_MISO, pin P3_8 = SSP0_MOSI. • SWD removed for ARM Cortex-M0. • BOD de-assertion levels added in Table 13. • Peripheral power consumption data added in Table 12. • Minimum value for all supply voltages changed to -0.5 V in Table 7.			

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